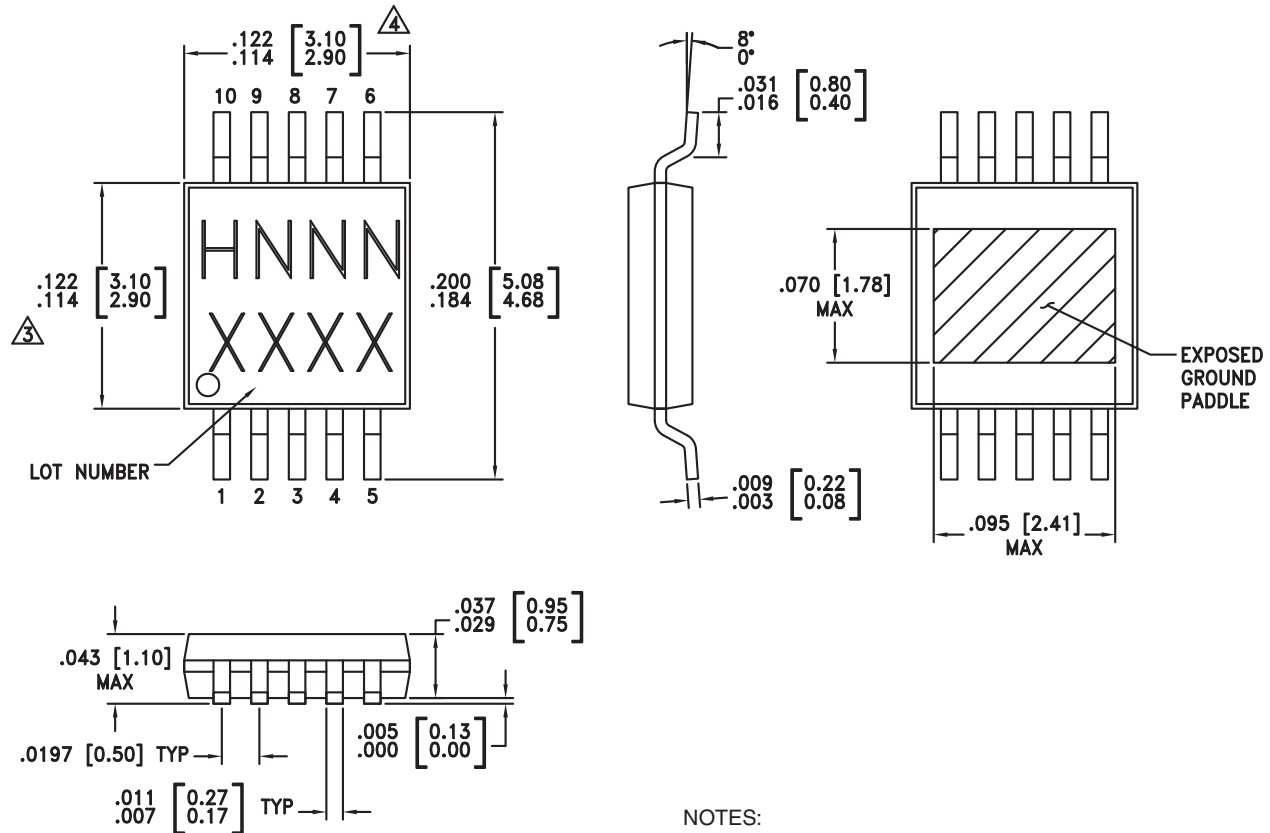


MS10G (E) – 10 LEAD PLASTIC MSOP PACKAGE WITH EXPOSED BASE

MS10G (E) Package Outline Drawing



NOTES:

- LEADFRAME MATERIAL: COPPER ALLOY
- DIMENSIONS ARE IN INCHES [MILLIMETERS]
- \triangle DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- \triangle DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
- ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number Suffix	Package Body Material	Lead Finish	MSL Rating	Package Marking ^{[3][4]}
MS10G	RoHS Compliant Mold Compound	Sn/Pb Solder	MSL1 ^[1]	HNNN XXXX
MS10GE	RoHS Compliant Mold Compound	100% matte Sn	MSL1 ^[2]	HNNN XXXX

[1] Max peak reflow temperature of 235 °C

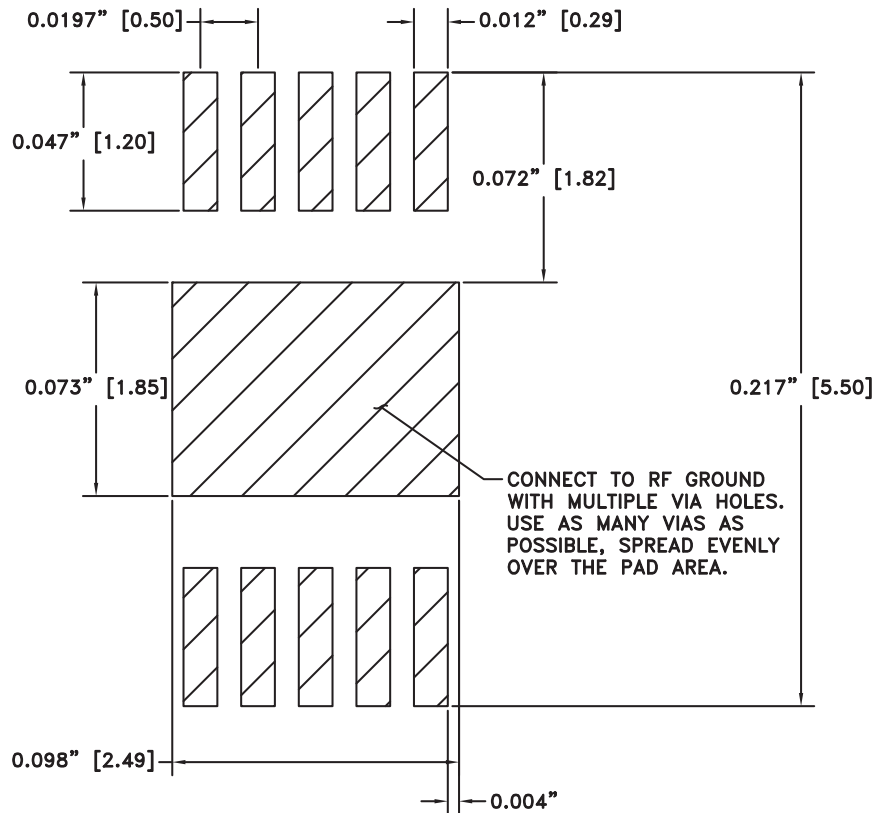
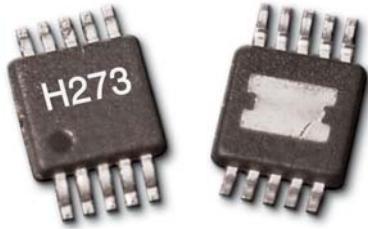
[2] Max peak reflow temperature of 260 °C

[3] 4-Digit lot number XXXX

[4] 3-Digit part number NNN

MS10G (E) – 10 LEAD PLASTIC MSOP PACKAGE WITH EXPOSED BASE

Suggested MS10G (E) PCB Land Pattern



NOTES:

1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.